

### 2 A max constant current LED driver

### **Features**

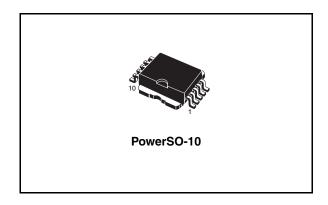
- Up to 40 V input voltage
- Less than 0.5 V voltage overhead
- Up to 2 A output current
- PWM dimming pin
- Shutdown pin
- LED disconnection diagnostic

## **Applications**

- LED constant current supplying for varying input voltages
- Low voltage lighting
- Small appliances LED lighting
- Car LED lights

## **Description**

The STCS2 is a BiCMOS constant current source designed to provide a precise constant current starting from a varying input voltage source. The main target is to replace discrete components solution for driving LEDs in low voltage applications such as 5 V, 12 V or 24 V giving benefits in terms of precision, integration and reliability.



The current is set with external resistor up to 2 A with a  $\pm$  10 % precision; a dedicated pin allows implementing PWM dimming.

An open-drain pin output provides information on load disconnection condition.

Table 1. Device summary

Order code	Package	Packaging
STCS2SPR	PowerSO-10	600 parts per reel

Contents STCS2

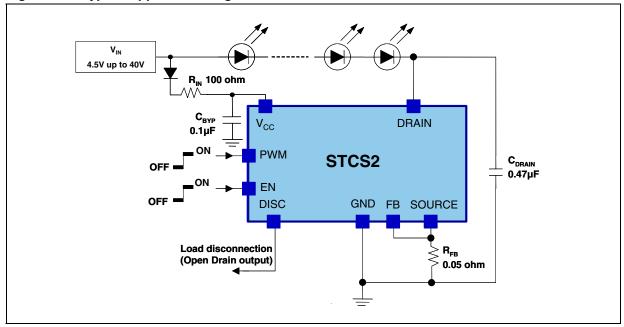
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STCS2 Application diagram

# 1 Application diagram

Figure 1. Typical application diagram for 2 A LED current



Pin configuration STCS2

# 2 Pin configuration

Figure 2. Pin connections (top view)

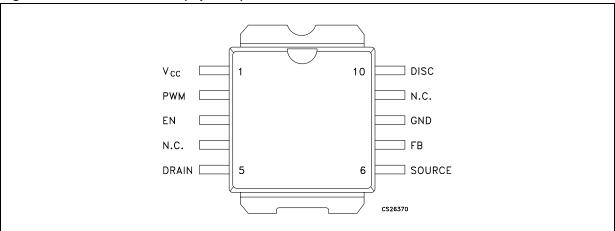


Table 2. Pin description

Pin n°	Symbol	Note
1	V <sub>CC</sub>	Supply voltage
2	PWM	PWM dimming input
3	EN	Shutdown
4	N.C.	Not connected
5	DRAIN	Internal N-MOSFET drain
6	SOURCE	Internal N-MOSFET SOURCE. Reference voltage is 100 mV. An external resistor between SOURCE and GND pins sets different current levels for different application needs
7	FB	Feedback input. The control loop regulates the current in such a way that the average voltage at the FB input is 100 mV (nominal). The cathode of the LED and a resistor to ground to set the LED current should be connected at this point
8	GND	Ground
9	N.C.	In order to guarantee the device works properly it is mandatory to leave this pin floating
10	DISC	Load disconnection flag (open drain)
	Exp-pad	Internally connected to ground

STCS2 Maximum ratings

## 3 Maximum ratings

Table 3. Absolute maximum ratings

Parameter	Value	Unit			
DC supply voltage	-0.3 to +45	V			
Drain pin	-0.3 to +45	V			
Source pin	-0.3 to + 3.3	V			
Logic pins	-0.3 to + V <sub>CC</sub> + 0.3	V			
Configuration pins	-0.3 to + 3.3	V			
Human body model (all pins)	±2	kV			
Junction temperature	-40 to 150	°C			
Storage temperature range	-55 to 150	°C			
	DC supply voltage Drain pin Source pin Logic pins Configuration pins Human body model (all pins) Junction temperature	DC supply voltage $-0.3$ to $+45$ Drain pin $-0.3$ to $+45$ Source pin $-0.3$ to $+3.3$ Logic pins $-0.3$ to $+$ V <sub>CC</sub> $+$ 0.3Configuration pins $-0.3$ to $+3.3$ Human body model (all pins) $\pm 2$ Junction temperature $-40$ to 150			

T<sub>J</sub> is calculated from the ambient temperature T<sub>A</sub> and the power dissipation P<sub>D</sub> according the following formula: T<sub>J</sub> = T<sub>A</sub> + (P<sub>D</sub> x R<sub>thJA</sub>). See Figure 12 for details of max power dissipation for ambient temperatures higher than 25°C.

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Note:

Table 4.

Absolute maximum ratings are those values beyond which damage to the device may occur. Functional operation under these conditions is not implied.

Symbol	Parameter	PowerSO-10	Unit
R <sub>thJC</sub>	Thermal resistance junction-case	2	°C/W
R <sub>thJA</sub>	Thermal resistance junction-ambient (1)	50	°C/W
R <sub>thJA</sub>	Thermal resistance junction-ambient (2)	35	°C/W
R <sub>thJA</sub>	Thermal resistance junction-ambient (3)	12	°C/W

<sup>1.</sup> FR4 with using the recommended pad-layout

Thermal data

<sup>2.</sup> FR4 with heat sink on board (6 cm<sup>2</sup>).

<sup>3.</sup> FR4 with copper-filled through holes and external heat sink applied.

Electrical characteristics STCS2

## 4 Electrical characteristics

Table 5. Electrical characteristics  $(V_{CC}=12~V;~I_O=100~mA;~T_J=-40~^{\circ}C~to~125~^{\circ}C;~V_{DRAIN}=1~V;~C_{DRAIN}=1~\mu\text{F};~C_{BYP}=100~n\text{F}~typical values are at }T_A=25~^{\circ}C,~unless~otherwise~specified)$ 

Symbol	Parameter	Test conditions	Min.	Тур.	Max.	Unit		
V <sub>CC</sub>	Supply voltage range		4.5		40	V		
	Output current range		1		2000	mA		
Io	Output current	$R_{FB} = 50 \text{ m}\Omega$		2		Α		
	Regulation (percentage with respect to V <sub>CC</sub> =12V)	V <sub>CC</sub> = 4.5 to 40 V, I <sub>O</sub> = 100 mA; V <sub>DRAIN</sub> = 1 V	-1		+1	%		
V <sub>FB</sub>	Feedback voltage	I <sub>O</sub> = 0 to 2A	90	100	110	mV		
		On Mode		450	750			
I <sub>CC</sub>	Quiescent current (Measured on V <sub>CC</sub> pin)	Shutdown Mode; V <sub>CC</sub> = 5 to 12V			1	μΑ		
	- CC P/	Shutdown Mode; V <sub>CC</sub> = 12 to 40V			3			
V	Dropout voltage (V to CND)	I <sub>O</sub> = 100 mA		0.12	0.16	V		
$V_{DROP}$	Dropout voltage (V <sub>DRAIN</sub> to GND)	I <sub>O</sub> = 2 A		0.58	0.9			
LEAK <sub>DRAIN</sub>	Drain leakage current	Shutdown; V <sub>DRAIN</sub> = 40 V			10	μΑ		
T <sub>D</sub>	Delay on PWM signal (see fig.1)	V <sub>PWM</sub> rising, V <sub>CC</sub> = 12 V		3		- µs		
'D	Delay on Pyvivi signal (see lig. 1)	V <sub>PWM</sub> falling, V <sub>CC</sub> = 12 V		1.2				
	Low level voltage	I <sub>SINK</sub> = 5 mA		0.2	0.5	٧		
DISC	Leakage current	V <sub>DISC</sub> = 5 V			1	μΑ		
DISC	Load disconnection threshold	DISC Turn-ON		75		mV		
	(V <sub>DRAIN</sub> -GND)	DISC Turn-OFF		110				
Thermal	Shutdown temperature			155		°C		
Protection	Hysteresis			25		1		
Logic input	s (PWM and EN)							
$V_{L}$	Input low level				0.4	V		
$V_{H}$	Input high level		1.2			V		
	EN, PWM leakage current	V <sub>EN</sub> = 5 V; V <sub>PWM</sub> = 5 V			2			
	EN input leakage current	V <sub>EN</sub> = 40 V			60	μΑ		
	PWM input leakage current	V <sub>PWM</sub> = 40 V			120	20		

Note: All devices 100 % production tested at  $T_A = 25$  °C. Limits over the operating temperature range are guaranteed by design.

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STCS2 Timing

# 5 Timing

Figure 3. PWM and output current timing

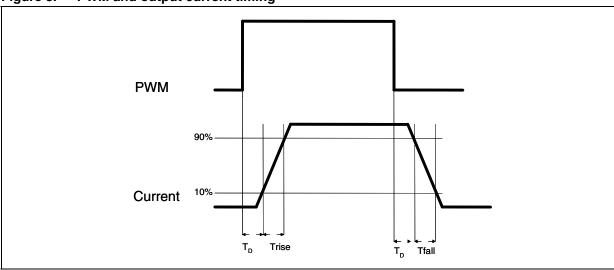
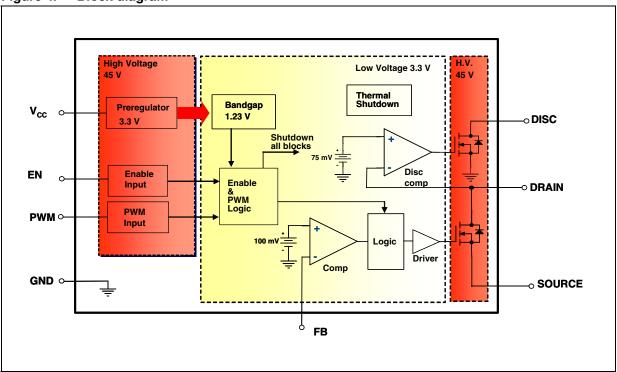


Figure 4. Block diagram



# **6** Typical performance characteristics

Figure 5.  $I_{DRAIN}$  vs  $V_{CC}$ ,  $T_A = 25$  °C

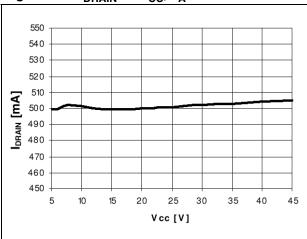


Figure 6.  $I_{DRAIN}$  vs  $R_{SET}$ 

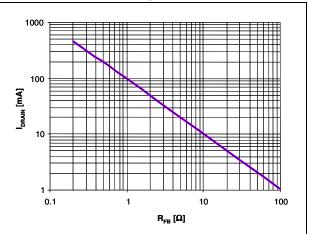


Figure 7. I<sub>DRAIN</sub> vs temperature

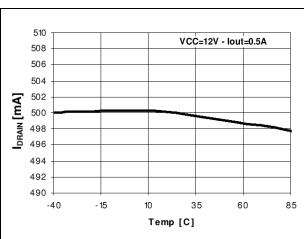


Figure 8. V<sub>DROP</sub> (including V<sub>FB</sub>) vs temperature

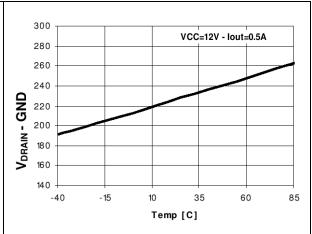


Figure 9. I<sub>CC</sub> vs temperature

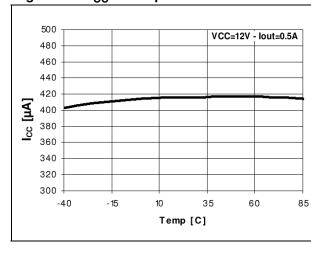
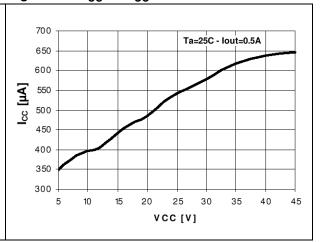


Figure 10.  $I_{CC}$  vs  $V_{CC}$ 



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STCS2 Detail description

## 7 Detail description

The STCS2 is a BiCMOS constant current source designed to provide a precise constant current starting from a varying input voltage source. The main target is to replace discrete components solution for driving LEDs in low voltage applications such as 5 V, 12 V or 24 V giving benefits in terms of precision, integration and reliability.

### 7.1 Current setting

The current is set with an external sensing resistor connected to the FB pin. The feedback voltage is 100 mV, then a low resistor value can be chosen reducing power dissipation. A value between 1 mA and 2 A can be set according to the resistor value the resulting output current has a tolerance of  $\pm$  10 %.

For instance, should one need a 700 mA LEDs current, R<sub>F</sub> should be selected according to the following equation:

 $R_F = V_{FB} / I_{LEDs} = 100 \text{ mV} / 700 \text{ mA} = 142 \text{ m}\Omega$ 

### 7.2 Enable

When the enable pin is low the device completely off thus reducing current consumption to less than 1  $\mu$ A. When in shutdown mode, the internal main switch is off.

## 7.3 PWM dimming

The PWM input allows implementing PWM dimming on the LED current; when the PWM input is high the main switch will be on and vice versa. A typical frequency range for the input is from few Hertz to 50 kHz. The maximum dimming frequency is limited by the minimum rise/fall time of the current which is around 4 µs each. Above 50 kHz the current waveforms starts assuming a triangular shape.

While the PWM input is switching, the overall circuitry remains on, this is needed in order to implement a short delay time  $T_D$  (see *Figure 3*).

Since the PWM pin is controlling just the main switch, the overall circuitry is always on and it is able to control the delay time between the PWM input signal and the output current in the range of few  $\mu$ s, this is important to implement synchronization among several light LED sources.

## 7.4 Diagnostic

When STCS2 is in on mode (EN is high), the device is able to detect disconnection or fail of the LED string monitoring  $V_{DRAIN}$  pin. If  $V_{DRAIN}$  is lower than 75 mV the DISC pin is pulled low regardless the PWM pin status. This information can be used by the system to inform that some problem happens in the LEDs.

#### 8 **Application information**

#### 8.1 Reverse polarity protection

STCS2 must be protected from reverse connection of the supply voltage. Since the current sunk from  $V_{CC}$  pin is in the range of 450  $\mu$ A a small diode connected to  $V_{CC}$  is able to protect the chip. Care must be taken for the whole application circuit, especially for the LEDs, in fact, in case a negative voltage is applied between V<sub>IN</sub> and GND, a negative voltage will be applied to the LED string that must have a total breakdown voltage higher than the negative applied voltage in order to avoid any damage.

 $\mathbf{V}_{\text{IN}}$ **DRAIN** DISC EN GND FB SOURCE RSENSE

Reverse polarity condition Figure 11.

#### 8.2 Thermal considerations

The STCS2 is able to control a LED current up to 2 A and able to sustain a voltage on the drain pin up to 40 V. Those operating conditions are however limited by thermal constraints.

The poor thermal conduction of epoxy FR4 boards does not permit to benefit of the outstanding thermal performance of the PowerSO-10.

In any case one way to improve the thermal conduction is the use of large heat spreader areas at the copper layer of the PC board. This leads to a reduction of thermal resistance to 30 - 36°C/W for 3 to 6 cm<sup>2</sup> on-board heatsink.

Use of copper-filled through holes on conventional FR4 techniques increases the metallization and decreases thermal resistance accordingly. Using a configuration with 16 holes under the spreader of the package with a pitch of 1.8 mm and a diameter of 0.7 mm, the thermal resistance (junction - heatsink) can be reduced to 12 °C/W.

The thermal resistances shown in the Error! Reference source not found, section are the typical ones.

The power dissipation in the device can be calculated as follow:

$$P_D = (V_{DRAIN} - V_{FB}) \times I_{LED} + (V_{CC} \times I_{CC})$$

basing on this and on the thermal resistance and ambient temperature, the junction temperature can be calculated as:

$$T_J = R_{thJA} \times P_D + T_A$$

A typical application could be:

- Input Voltage: 12 V;
- 3 white LEDs with an typical  $V_F = 3.6 \text{ V}$ ;
- LEDs current: 1000 mA;
- Package: Power SO-10;
- T<sub>A</sub> = 50 °C;

In this case the drain voltage is given by:

$$V_{DRAIN} = 12 - 3 \times 3.6 = 1.2 \text{ V}$$

end the power dissipated in the IC is the following:

$$P_D = (1.2 - 0.1) \times 1 + 12 \times 0.5 \times 10^{-3} = 1.1 \text{ W}$$

With a thermal resistance junction-ambient equal to 12 °C/W the junction temperature is:

$$T_J = 12 \times 1.1 + 50 = 63 \,^{\circ}\text{C}.$$

The following pictures show the maximum power dissipation according to the ambient temperature:

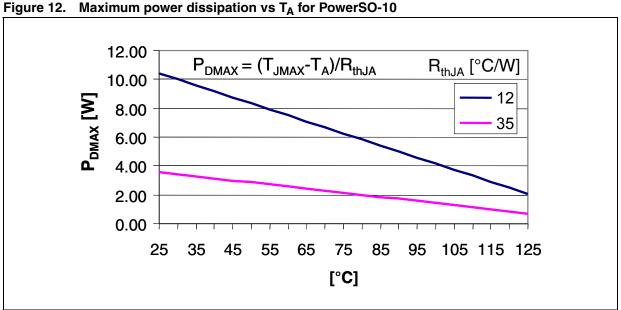


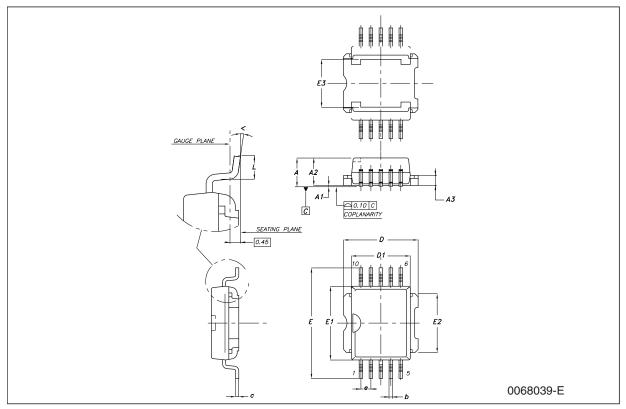
Figure 12.

# 9 Package mechanical data

In order to meet environmental requirements, ST offers these devices in ECOPACK<sup>®</sup> packages. These packages have a lead-free second level interconnect. The category of second Level Interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

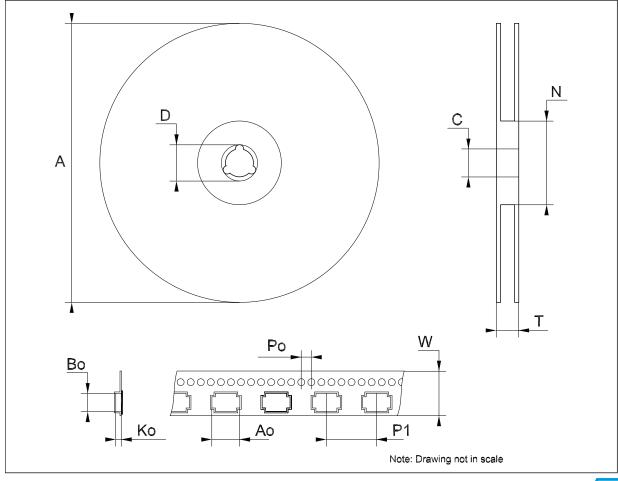
## PowerSO-10 mechanical data

Dim.	mm.			inch.		
Dilli.	Min.	Тур.	Max.	Min.	Тур.	Max.
А			3.70			0.146
A1			0.10			0.004
A2	3.40		3.60	0.134		0.142
А3	1.25		1.35	0.049		0.053
b	0.40		0.53	0.016		0.021
С	0.35		0.55	0.014		0.022
D	9.40		9.60	0.370		0.378
D1	7.40		7.60	0.291		0.299
E	13.80		14.40	0.543		0.567
E1	9.30		9.50	0.366		0.374
E2	7.20		7.60	0.283		0.299
E3	5.90		6.10	0.232		0.240
е		1.27			0.050	
L	0.95		1.65	0.037		0.065
α	0°		8°	0°		8°



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Dim.	mm.			inch.		
	Min.	Тур.	Max.	Min.	Тур.	Max.
А			330			12.992
С	12.8		13.2	0.504		0.519
D	20.2			0.795		
N	60			2.362		
Т			30.4			1.197
Ao	14.9		15.1	0.587		0.594
Во	9.9		10.1	0.390		0.398
Ko	4.15		4.35	0.163		0.171
Ро	3.9		4.1	0.153		0.161
Р	23.9		24.1	0.941		0.949
W	23.7		24.3	0.933		0.957



STCS2 Revision history

# 10 Revision history

Table 6. Document revision history

Date	Revision	Changes	
03-Oct-2007	1	Initial release.	
15-Feb-2008	2	Modified: Figure 1 on page 3, Figure 4 on page 7, Figure 12 on page 11.	
05-May-2008 3 Modified: <i>Table 2 on page 4</i> , pin 9 description.		Modified: Table 2 on page 4, pin 9 description.	
02-Jul-2008	4	Modified: Table 5 on page 6.	

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